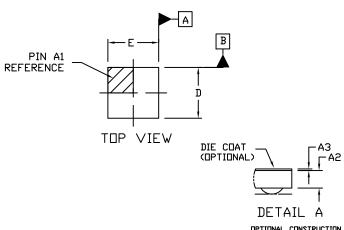
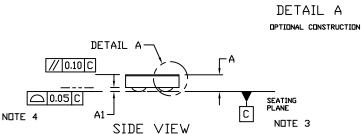


WLCSP4, 0.77x0.77x0.3 CASE 567VX ISSUE O

DATE 13 FEB 2018



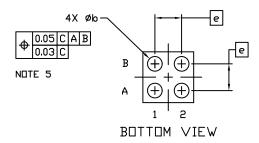


2. CO

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE CONTACT BALLS.
- 4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
- 5. DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALLS DIAMETER PARALLEL TO TO DATUM C.
- 6. BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS		
DIM	MIN.	N□M.	MAX.
Α	0.25	0.275	0.30
A1	0.04	0.06	0.08
A2	0.19 REF		
A3	0.025 REF		
b	0.20	0.22	0.24
D	0.72	0.77	0.82
Е	0.72	0.77	0.82
e	0.40 BSC		



GENERIC MARKING DIAGRAM*

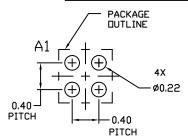


X = Specific Device Code

Y = Year

W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " • ", may or may not be present. Some products may not follow the Generic Marking.



RECOMMENDED MOUNTING FOOTPRINT

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